

74LCX244

Low Voltage Buffer/Line Driver with 5V Tolerant Inputs and Outputs

General Description

The LCX244 contains eight non-inverting buffers with 3-STATE outputs. The device may be employed as a memory address driver, clock driver and bus-oriented transmitter/receiver. The LCX244 is designed for low voltage (3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment.

The LCX244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

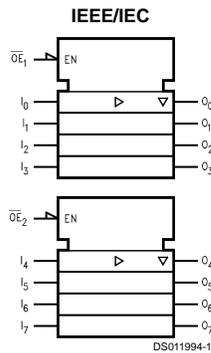
- 5V tolerant inputs and outputs
- 6.5 ns t_{PD} max, 10 μA I_{CCQ} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal
- 2.0V–3.6V V_{CC} supply operation
- ± 24 mA output drive
- Implements patented noise/EMI reduction circuitry
- Functionally compatible with the 74 series 244
- Latch-up performance exceeds 500 mA
- ESD performance: Human body model > 2000V; Machine model > 200V

Ordering Code:

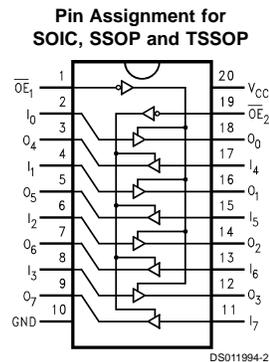
Order Number	Package Number	Package Description
74LCX244WM	M20B	20-Lead (0.300" Wide) Molded Small Outline Package, SOIC JEDEC
74LCX244SJ	M20D	20-Lead. Small Outline Package, SOIC EIAJ
74LCX244MSA	MSA20	20-Lead Molded Shrink Small Outline Package, SSOP Type II
74LCX244MTC	MTC20	20-Lead Thin Skrink Small Outline Package, TSSOP JEDEC

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
I_0-I_7	Inputs
O_0-O_7	Outputs

Truth Tables

Inputs		Outputs (Pins 12, 14, 16, 18)
\overline{OE}_1	I_n	
L	L	L
L	H	H
H	X	Z

Inputs		Outputs (Pins 3, 5, 7, 9)
\overline{OE}_2	I_n	
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
 X = Immaterial
 L = LOW Voltage Level
 Z = High Impedance

Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Value	Conditions	Units
V_{CC}	Supply Voltage	-0.5 to +7.0		V
V_I	DC Input Voltage	-0.5 to +7.0		V
V_O	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to $V_{CC} + 0.5$	Output in High or Low State (Note 2)	V
I_{IK}	DC Input Diode Current	-50	$V_I < GND$	mA
I_{OK}	DC Output Diode Current	-50	$V_O < GND$	mA
		+50	$V_O > V_{CC}$	
I_O	DC Output Source/Sink Current	± 50		mA
I_{CC}	DC Supply Current per Supply Pin	± 100		mA
I_{GND}	DC Ground Current per Ground Pin	± 100		mA
T_{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions (Note 3)

Symbol	Parameter	Min	Max	Units	
V_{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	
V_I	Input Voltage	0	5.5	V	
V_O	Output Voltage	HIGH or LOW State	0	V_{CC}	V
		3-STATE	0	5.5	
I_{OH}/I_{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		± 24	mA
		$V_{CC} = 2.7V$		± 12	
T_A	Free-Air Operating Temperature	-40	85	°C	
$\Delta t/\Delta V$	Input Edge Rate, $V_{IN} = 0.8V - 2.0V$, $V_{CC} = 3.0V$	0	10	ns/V	

Note 1: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: I_O Absolute Maximum Rating must be observed.

Note 3: Unused (inputs or I/Os) must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40^\circ C$ to $+85^\circ C$		Units
				Min	Max	
V_{IH}	HIGH Level Input Voltage		2.7-3.6	2.0		V
V_{IL}	LOW Level Input Voltage		2.7-3.6		0.8	V
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -100 \mu A$	2.7-3.6	$V_{CC} - 0.2$		V
		$I_{OH} = -12 mA$	2.7	2.2		V
		$I_{OH} = -18 mA$	3.0	2.4		V
		$I_{OH} = -24 mA$	3.0	2.2		V
V_{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.7-3.6		0.2	V
		$I_{OL} = 12 mA$	2.7		0.4	V
		$I_{OL} = 16 mA$	3.0		0.4	V
		$I_{OL} = 24 mA$	3.0		0.55	V
I_I	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.7-3.6		± 5.0	μA
I_{OZ}	3-STATE Output Leakage	$0 \leq V_O \leq 5.5V$ $V_I = V_{IH}$ or V_{IL}	2.7-3.6		± 5.0	μA
I_{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μA
I_{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.7-3.6		10	μA
		$3.6V \leq V_I, V_O \leq 5.5V$	2.7-3.6		± 10	μA
ΔI_{CC}	Increase in I_{CC} per Input	$V_{IH} = V_{CC} - 0.6V$	2.7-3.6		500	μA

AC Electrical Characteristics

Symbol	Parameter	$T_A = -40^\circ\text{C to } +85^\circ\text{C}, C_L = 50\text{pF}, R_L = 500\ \Omega$				Units
		$V_{CC} = 3.3\text{V} \pm 0.3\text{V}$		$V_{CC} = 2.7\text{V}$		
		Min	Max	Min	Max	
t_{PHL}	Propagation Delay	1.5	6.5	1.5	7.5	ns
t_{PLH}	Data to Output	1.5	6.5	1.5	7.5	
t_{PZL}	Output Enable Time	1.5	8.0	1.5	9.0	ns
t_{PZH}		1.5	8.0	1.5	9.0	
t_{PLZ}	Output Disable Time	1.5	7.0	1.5	8.0	ns
t_{PHZ}		1.5	7.0	1.5	8.0	
t_{OSHL}	Output to Output Skew (Note 4)		1.0			ns
t_{OSLH}			1.0			

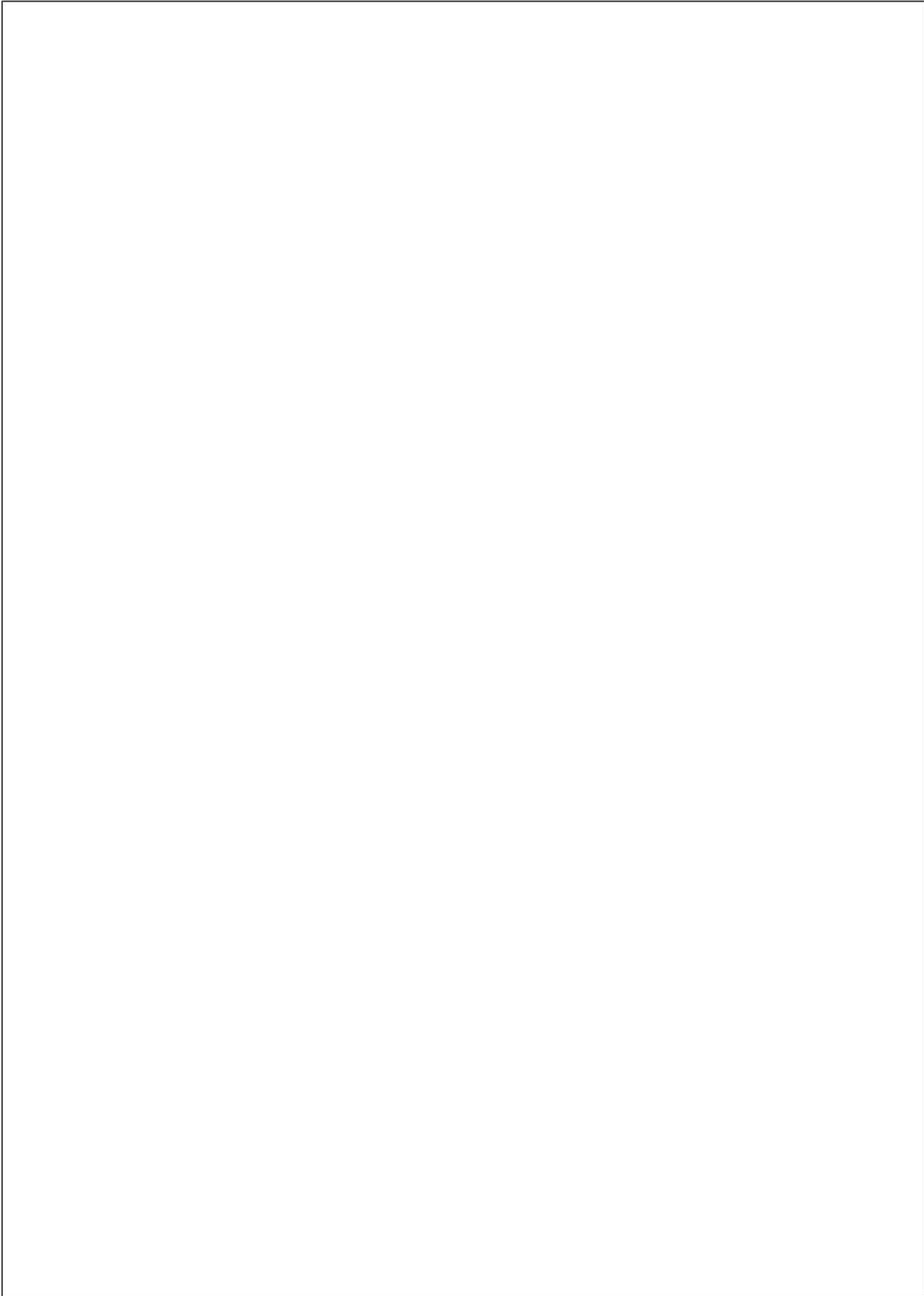
Note 4: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH to LOW (t_{OSHL}) or LOW to HIGH (t_{OSLH}).

Dynamic Switching Characteristics

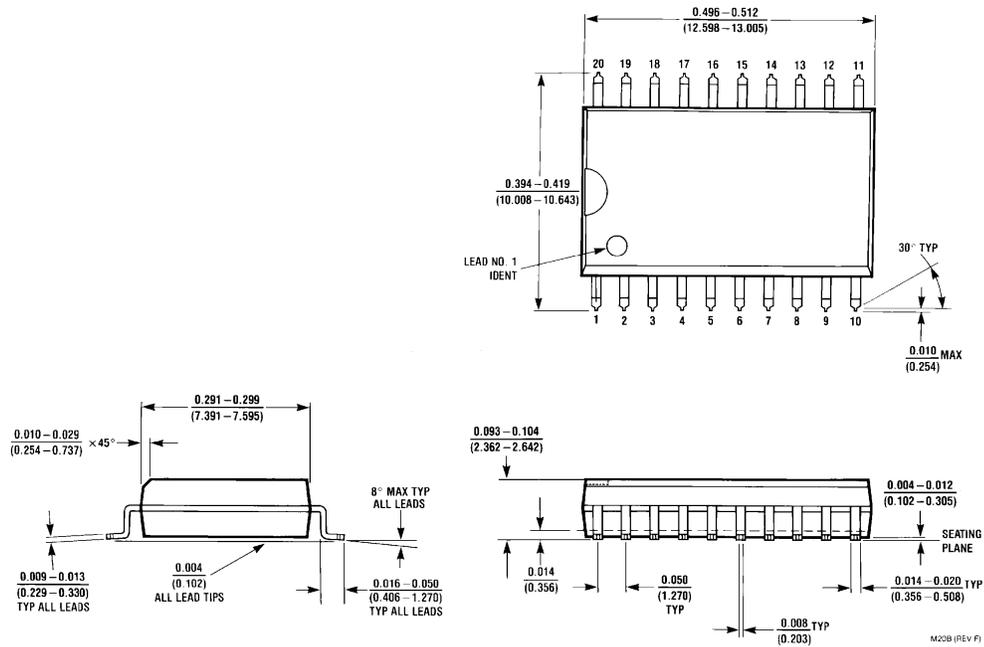
Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$	Units
				Typical	
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	$C_L = 50\ \text{pF}, V_{IH} = 3.3\text{V}, V_{IL} = 0\text{V}$	3.3	0.8	V
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	$C_L = 50\ \text{pF}, V_{IH} = 3.3\text{V}, V_{IL} = 0\text{V}$	3.3	-0.8	V

Capacitance

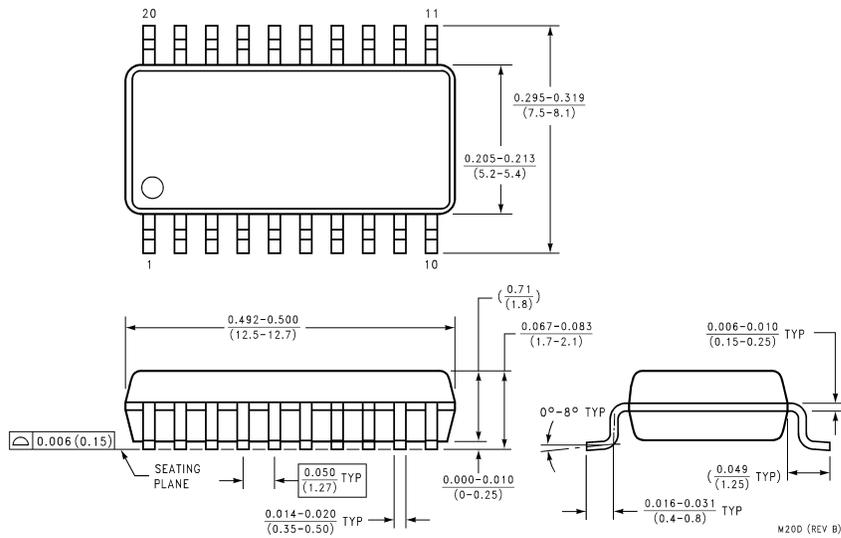
Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = \text{Open}, V_I = 0\text{V or } V_{CC}$	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}$	8	pF
C_{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}, f = 10\ \text{MHz}$	25	pF



Physical Dimensions inches (millimeters) unless otherwise noted

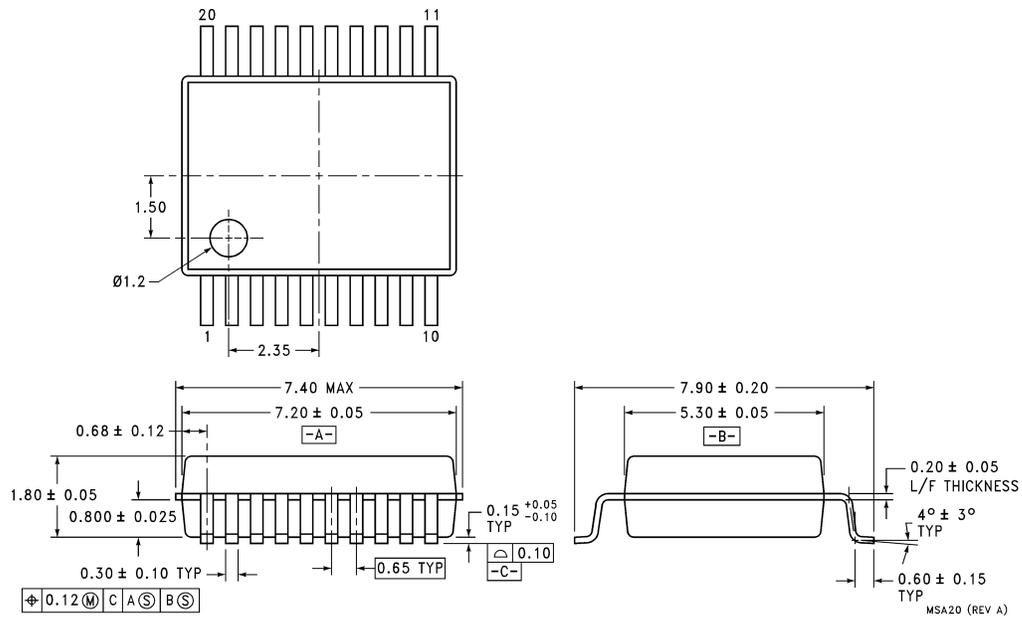


**20-Lead (0.300" Wide) Molded Small Outline Package, JEDEC
Package Number M20B**



**20-Lead Small Outline Package, EIAJ (SJ)
Package Number M20D**

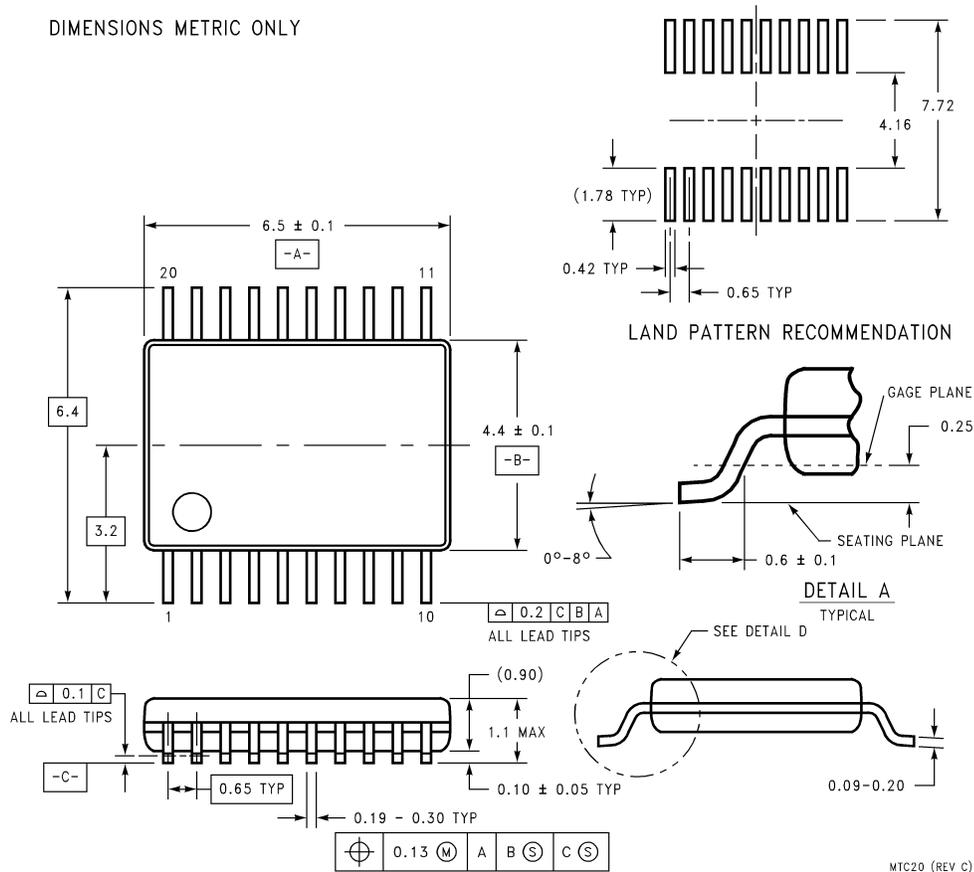
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Molded Shrink Small Outline Package, EIAJ, Type II
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

DIMENSIONS METRIC ONLY



**20-Lead Thin Shrink Small Outline Package, JEDEC
Package Number MTC20**

MTC20 (REV C)

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Fairchild Semiconductor Corporation Americas
Customer Response Center
Tel: 1-888-522-5372

Fairchild Semiconductor Europe
Fax: +49 (0) 1 80-530 85 86
Email: europe.support@nsc.com
Deutsch Tel: +49 (0) 8 141-35-0
English Tel: +44 (0) 1 793-85-68-56
Italy Tel: +39 (0) 2 57 5631

Fairchild Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd.
Tsimshatsui, Kowloon
Hong Kong
Tel: +862 2737-7200
Fax: +852 2314-0061

National Semiconductor Japan Ltd.
Tel: 81-3-5620-6175
Fax: 81-3-5620-6179

www.fairchildsemi.com